Overvoltage Transient Suppressor

Designed for applications requiring a low voltage rectifier with reverse avalanche characteristics for use as reverse power transient suppressors. Developed to suppress transients in the automotive system, these devices operate in the forward mode as standard rectifiers or reverse mode as power avalanche rectifier and will protect electronic equipment from overvoltage conditions.

Features

- High Power Capability
- Economical
- Increased Capacity by Parallel Operation
- Pb–Free Packages are Available*

Mechanical Characteristics:

- Case: Epoxy, Molded
- Weight: 2.5 Grams (Approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Maximum Lead Temperature for Soldering Purposes: 350°C 3/8″ from Case for 10 Seconds at 5 lbs. Tension
- Polarity: Indicated by Diode Symbol or Cathode Band

MAXIMUM RATINGS (T_J = 25°C unless otherwise noted)

Rating	Symbol	Value	Unit
DC Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	23	V
Repetitive Peak Reverse Surge Current (Time Constant = 10 ms, Duty Cycle \leq 1%, T _C = 25°C)	I _{RSM}	58	A
Peak Reverse Power (Time Constant = 10 ms, Duty Cycle \leq 1%, T _C = 25°C)	P _{RSM}	2500	W
Average Rectified Forward Current , (Single Phase, Resistive Load, 60 Hz, $T_C = 125^{\circ}C$) (See Figure 4)	Ι _Ο	6.0	A
Non–Repetitive Peak Surge Current, Surge Supplied at Rated Load Conditions Halfwave, Single Phase	I _{FSM}	400	A
Operating and Storage Junction Temperature Range	T _J , T _{stg}	65 to +175	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

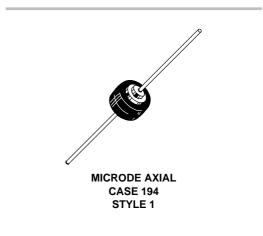
*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.



ON Semiconductor®

http://onsemi.com

OVERVOLTAGE TRANSIENT SUPPRESSOR 24 – 32 VOLTS



MR2520LAYYWW • •

MARKING DIAGRAM

A = Assembly Location YY = Year

- WW = Work Week
- = Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

THERMAL CHARACTERISTICS

Characteristic	Lead Length	Symbol	Max	Unit
Thermal Resistance, Junction-to-Lead, Both Leads to Heat Sink with Equal Length	6.25 mm 10 mm 15 mm	R _{θJL}	7.5 10 15	°C/W
Thermal Resistance Junction-to-Case	-	$R_{ extsf{ heta}JC}$	1.0	°C/W

ELECTRICAL CHARACTERISTICS ($T_J = 25^{\circ}C$ unless otherwise noted)

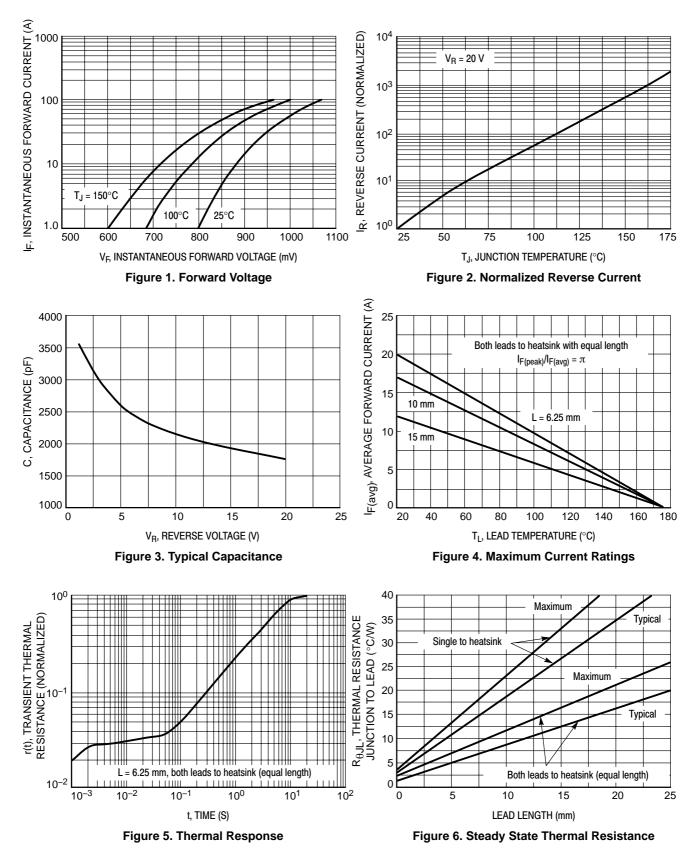
Characteristic	Symbol	Min	Max	Unit
Instantaneous Forward Voltage (Note 1) ($I_F = 100 \text{ A}, T_C = 25^{\circ}\text{C}$)	V _F	-	1.25	V
Instantaneous Forward Voltage (Note 1) $(I_F = 6.0 \text{ A}, T_C = 25^{\circ}\text{C})$	V _F	-	0.90	V
Reverse Current ($V_R = 20$ Vdc, $T_C = 25^{\circ}C$)	I _R	-	10	nAdc
Reverse Current ($V_R = 20$ Vdc, $T_C = 25^{\circ}C$)	I _R	-	300	nAdc
Breakdown Voltage (Note 1) ($I_R = 100 \text{ mAdc}, T_C = 25^{\circ}C$)	V _(BR)	24	32	V
Breakdown Voltage (Note 1) (I _R = 90 A, T _C = 150°C, PW = 80 μ s)	V _(BR)	-	40	V
Dynamic Resistance (I _R = 100 mA, T _J = 25°C, f = 1.0 kHz)	R _Z	-	5.0	Ω
Dynamic Resistance (I _R = 40 mA, T _J = 25°C)	R _Z	-	0.15	Ω
Breakdown Voltage Temperature Coefficient	V _{(BR)TC}	-	0.09*	%/°C
Forward Voltage Temperature Coefficient @ $I_F = 10 \text{ mA}$	V _{FTC}	-	-2*	mV/°C
Forward Voltage Temperature Coefficient @ $I_F = 10 \text{ mA}$	V _{FTC}	-	-2*	mV/°C

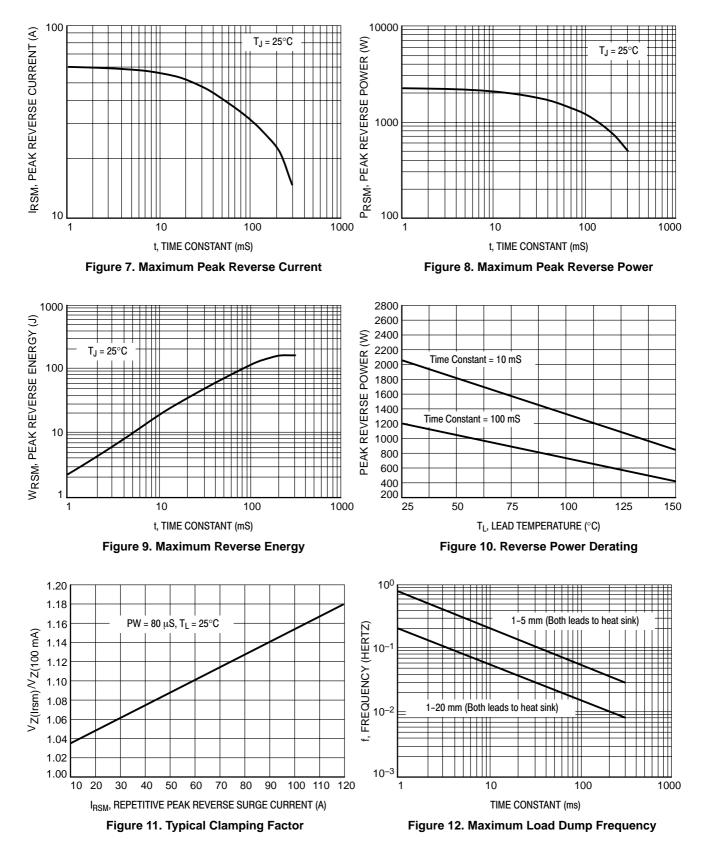
1. Pulse Test: Pulse Width \leq 300 $\mu s,$ Duty Cycle \leq 2%. *Typical

ORDERING INFORMATION

Device	Package	Shipping [†]
MR2520L	Microde Axial	
MR2520LG	Microde Axial (Pb–Free)	1000 / Box
MR2520LRL	Microde Axial	
MR2520LRLG	Microde Axial (Pb–Free)	800 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.





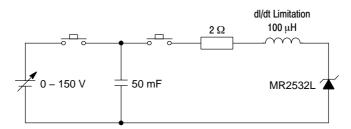


Figure 13. Load Dump Test Circuit

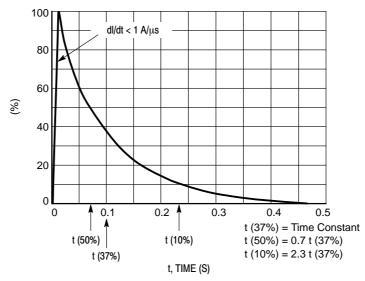
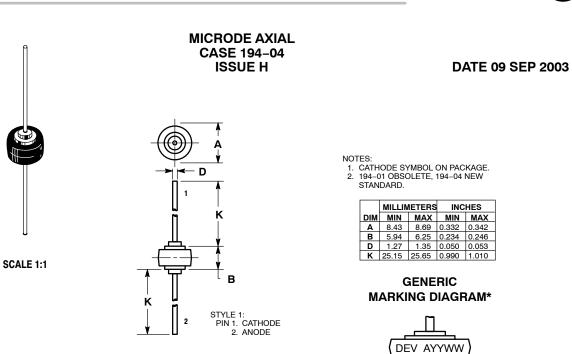


Figure 14. Load Dump Pulse Current



DEV = Specific Device Code

A = Assembly Location YY = Year

WW = Work Week

*This information is generic. Please refer to device data sheet for actual part marking.

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PUBLICATION ORDERING INFORMATION

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